

JLC Trigger and DAQ



Presented at the 4th International Workshop on Linear Colliders

May 3, Sitges, Barcelona, Spain

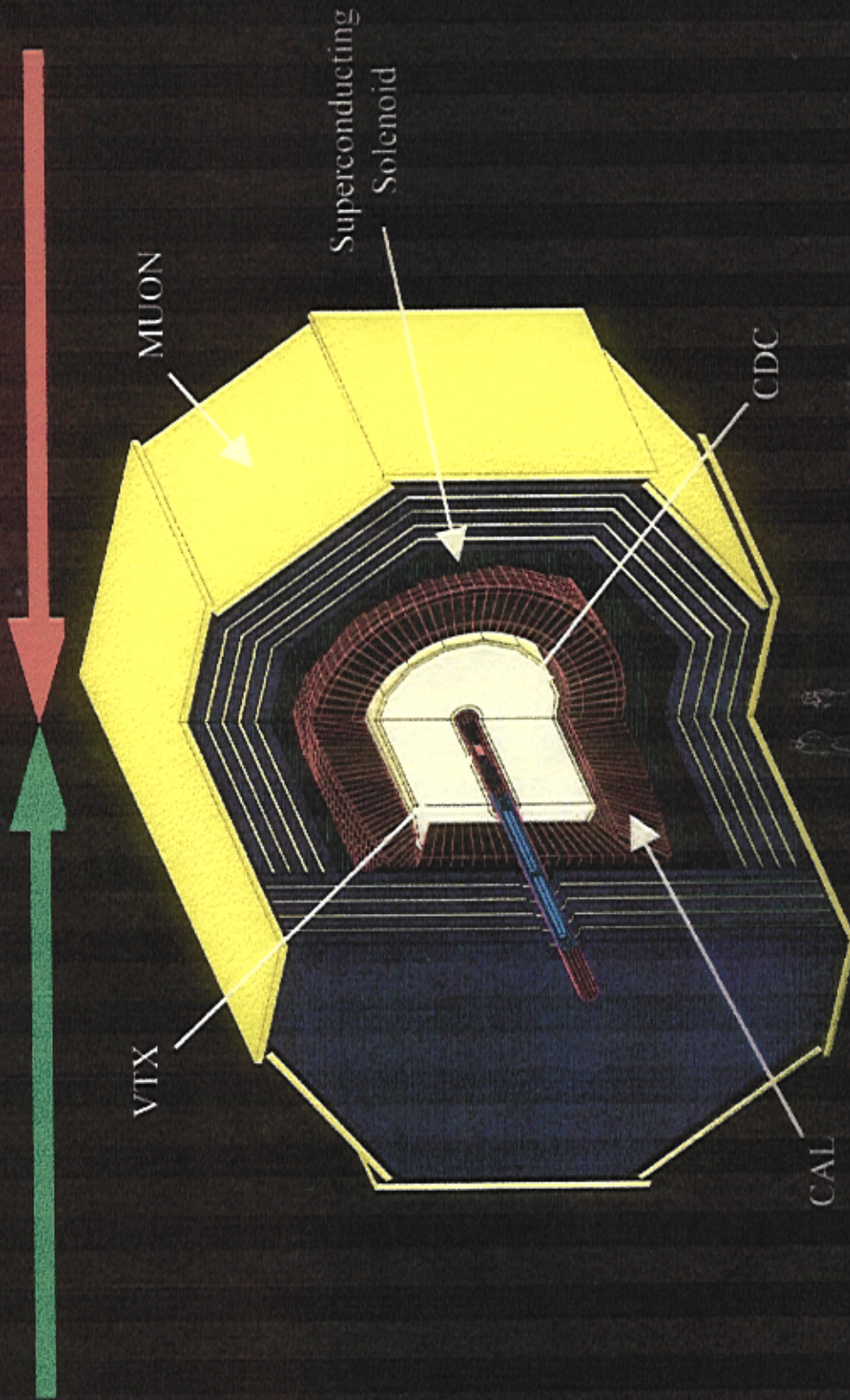
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4th International Workshop on Linear Colliders

JLC Detector



JLC Detector Parameters

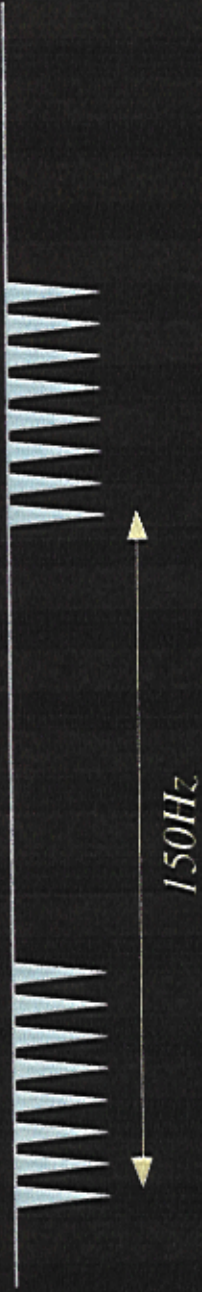
| Detector | Type | Configuration / Read-out | Performance |
|----------|---|---|--|
| VTX | Silicon CCD | Pixel size: 25 μ m Number of layers: 4 Layer position: 2.4/3.6/4.8/6.0cm Thickness: 200 μ m/layer $ \cos\theta < 0.9$ | Position resolution: $\sigma = 4\mu$ m Impact parameter resolution δ (μ m): $\delta^2 = 7^2 + (20.0/p)^2 / \sin^2\theta$ |
| CDC | Small-cell Jet Chamber | Radius: 0.4-2.3m Length: 4.6m Number of sampling: 86 $ \cos\theta < 0.70$ (Full sampling) $ \cos\theta < 0.95$ (20 sampling) | Position resolution: $\sigma_x = 86\mu$ m (by axial wires) $\sigma_y = 2\text{mm}$ (by stereo wires) Momentum resolution: $\sigma_{p_x} = 1.1 \times 10^{-3} p \oplus 0.1\%$ $\sigma_{p_y} = 5 \times 10^{-3} p \oplus 0.1\%$ with vertex constraint |
| CAL | Lead + Plastic Scintillator Sandwich (Compensated) | EM Thickness: 29X ₀ Cell size: 10cm x 10cm | Energy resolution: $\sigma_E/E = 15\% / \sqrt{E} \oplus 1\%$ (e & γ) $\sigma_E/E = 40\% / \sqrt{E} \oplus 2\%$ (Hadron) |
| | | HAD Thickness: 5.6X ₀ Cell size: 20cm x 20cm Longitudinal segment: 2 segments | |
| | | Si pad Pad size: 1cm x 1cm $ \cos\theta < 0.9$ | |
| MUCN | TGC RPC Drift Chamber | Number of superlayers: 5 $ \cos\theta < 0.90$ | Position resolution: ~mm P1 > 2.0 GeV/c, Reach return yoke P1 > 5.0 GeV/c, Penetrate return yoke |

Basic Concepts



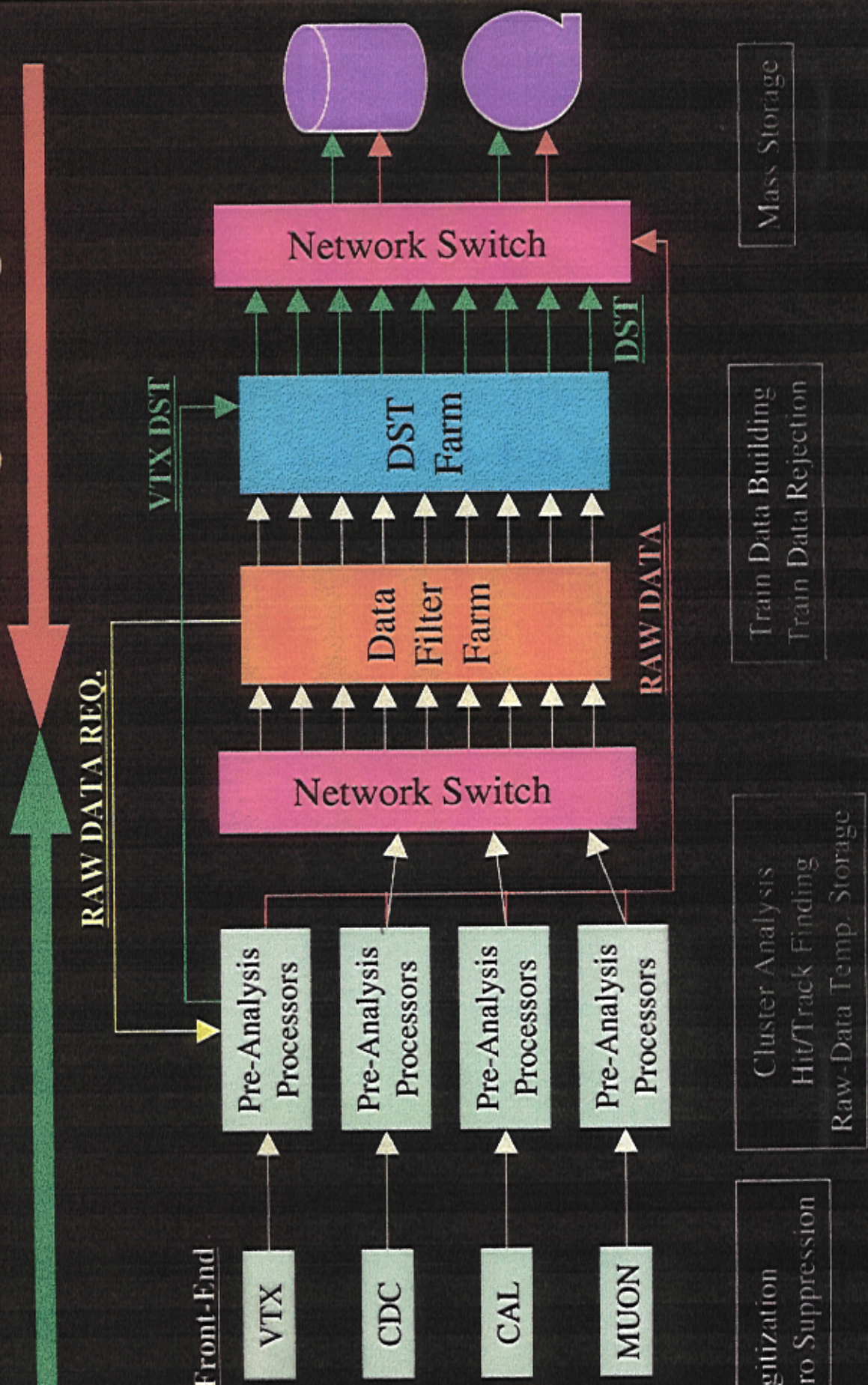
- JLC Beam Structure

85 Bunches
2.8 ns Spacing



- No Hardware Trigger Logic
- DAQ Triggered by Every Train Crossing
- Bunch ID provided by Off-line Analysis
 - CAL Timing & CDC T0 Fitting

JLC DAQ Diagram



Data Read-out



- DAQ Repetition Rate @ 150Hz
- Digitization, Zero Suppression
- in the Front-End Electronics
- Dead-Time Free

| Subsystems | Channel Count | | Typical Data Size (bytes) |
|------------|---------------|-----------|------------------------------|
| | Total | One Event | |
| VTX | 320M | 360K | 1.4M |
| CDC | 17M | 3M | 12M |
| CAL | 2.1M | 7.8K | 32K |
| MUON | TBD | TBD | TBD |
| Total | 340M | 3.4M | 13.5M |

VTX Read-out

- CCD VTX
 - 4 Layers ($R = 2.4/3.6/4.8/6.0$ cm), $|\cos\theta| < 0.9$
 - 25mmx5mm CCD Pad (200K $25\mu\text{m}^2$ Pixels/Pad)
 - 1600 CCD Pads (~ 320M Pixels)
 - FADC Read-out @ Each CCD Pad
 - Read-out Time 4 ms @ 50 MHz Sampling
 20 ms @ 10 MHz Sampling
 - 40 K Hits/Train including Noise/BG Tracks
 - Zero Suppression (3x3 Pixels around Peak)
 - 4 bytes/Pixel \rightarrow 1.4 Mbytes/Train


CDC Read-out

- Small-Cell Jet-Chamber
 - 1200 Cells, 7-Sense Wires/Cell
 - 17 K FADC Channels (Both End of a Wire)
 - 200 MHz 12-bit Sampling
 - Full Drift $\sim 5\mu\text{s}$ (=Read-out Time)
 - 100 Time-Slice (500 ns)/Hit by Zero Suppression
 - 30 K Hits/Train including Mini-jet Background
 - 4 bytes/Time-Slice \rightarrow 12 Mbytes/Train


CAL Read-out

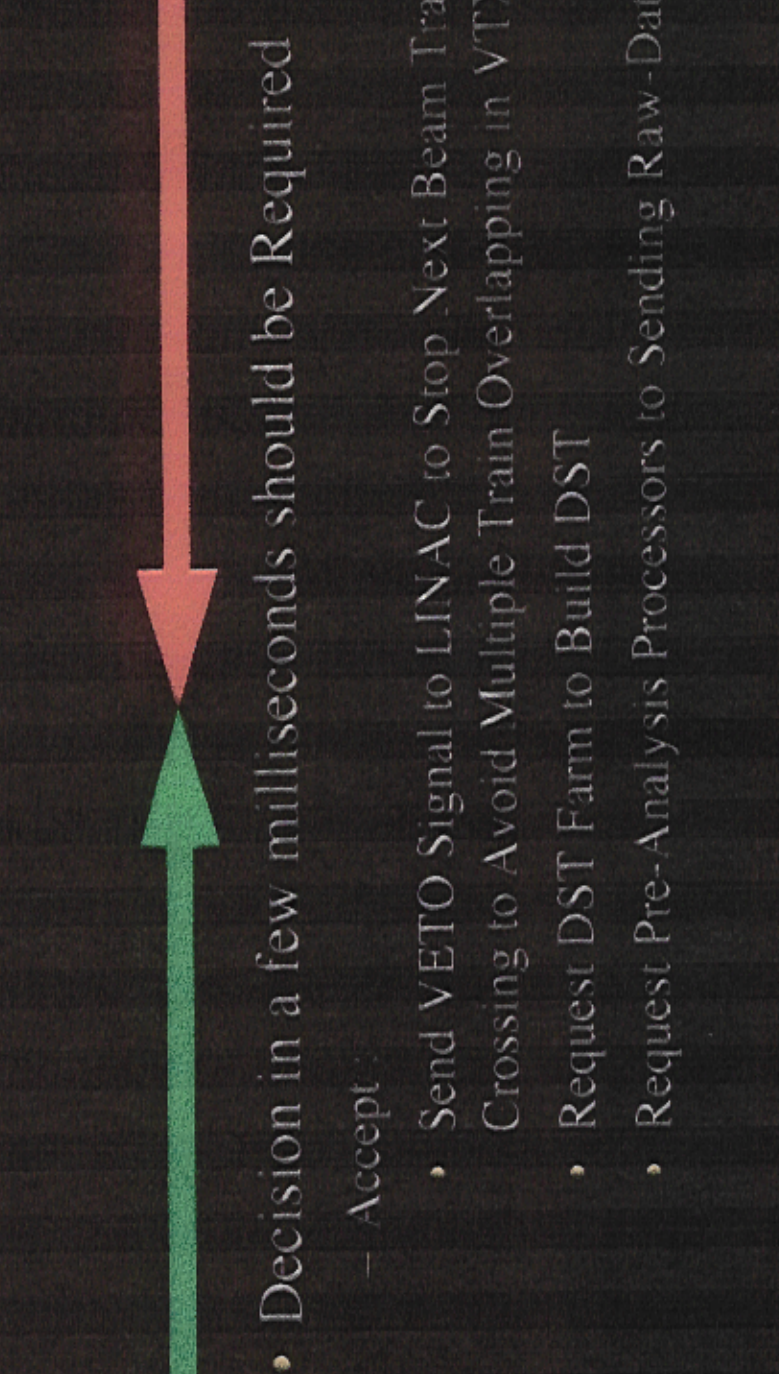
- Lead-Plastic Scintillator Sandwich
 - ECAL 10 cm² 20 K Channels
 - HCAL 20 cm² × 2 Segments 10 K Channels
 - Silicon Pad 1 cm² 2 M Channels
- 12-bit ADC Read-out
- 100 ns Data Conversion
- Multiplexed Read-out for Si Pads
- Zero Suppression
 - 12 K Data for ECAL, 0.6 K Data for HCAL
 - 6 K Data for Silicon Pads
 - 4 bytes/Flits → 32 Kbytes/Train

Data Reduction



- 3-stage Data Reduction
 - Pre-Analysis Processors
 - Installed in Each Sub-detector
 - Hardware Sequencer or Software Processing
 - Provide Cluster/Hit/Track to Data Filter Farm
 - Temporary Storage Buffer of Raw-Data
 - Expected Data Size to Data Filter ~ 1/10 of Raw Data
 - 100 Time-Slices/Hit in CDC
 - Several Words (Time-Stamp/Charge...)
 - Sum-up ADC Value in a Cluster in ECAL/HCAL

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- Data Filter Farm
 - Multiple CPU Complex
 - Reject Data containing **ONLY Mini-Jet Background** based on CDC/CAL Track/Cluster Information
 - Number of High P_T Tracks in CDC (Fast Track Recognition)
 - Total or Segmented Energy Flow in CAL
 - VTX Information is NOT Available (Slow Read-out)
 - Expected Rejection Factor
 - **10~20** @ $\sqrt{s} = 0.5 \sim 1.5$ TeV
 - No Rejection @ Z^0 Peak
 - Every Train contain "Physics Processes"

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- Decision in a few milliseconds should be Required
 - Accept
 - Send VETO Signal to LINAC to Stop Next Beam Train Crossing to Avoid Multiple Train Overlapping in VTX
 - Request DST Farm to Build DST
 - Request Pre-Analysis Processors to Sending Raw-Data
 - Reject
 - Clear Frond-End Electronics and Pre-Analysis Processors
 - VTX Needs 1 ms to Clear CCD



– On-line DST Production

- Multiple CPU Complex
- DST Contains
 - VTX Cluster, CDC Hit, CAL Cluster... From Pre-Analysis
 - CDC Track, Energy Flow in CAL... From Data Filter
- Data Size of DST *~ 1 Mbytes/Train*
- Seriously Required for DAQ @ Z^0 Peak
 - No Rejection by Data Filter
 - Limited Data Recording Speed
 - Give-up Raw-Data Recording ²⁰⁰⁹

Data Recording

– Raw Data Recording @ $\sqrt{s} = 0.5 \sim 1.5$ TeV

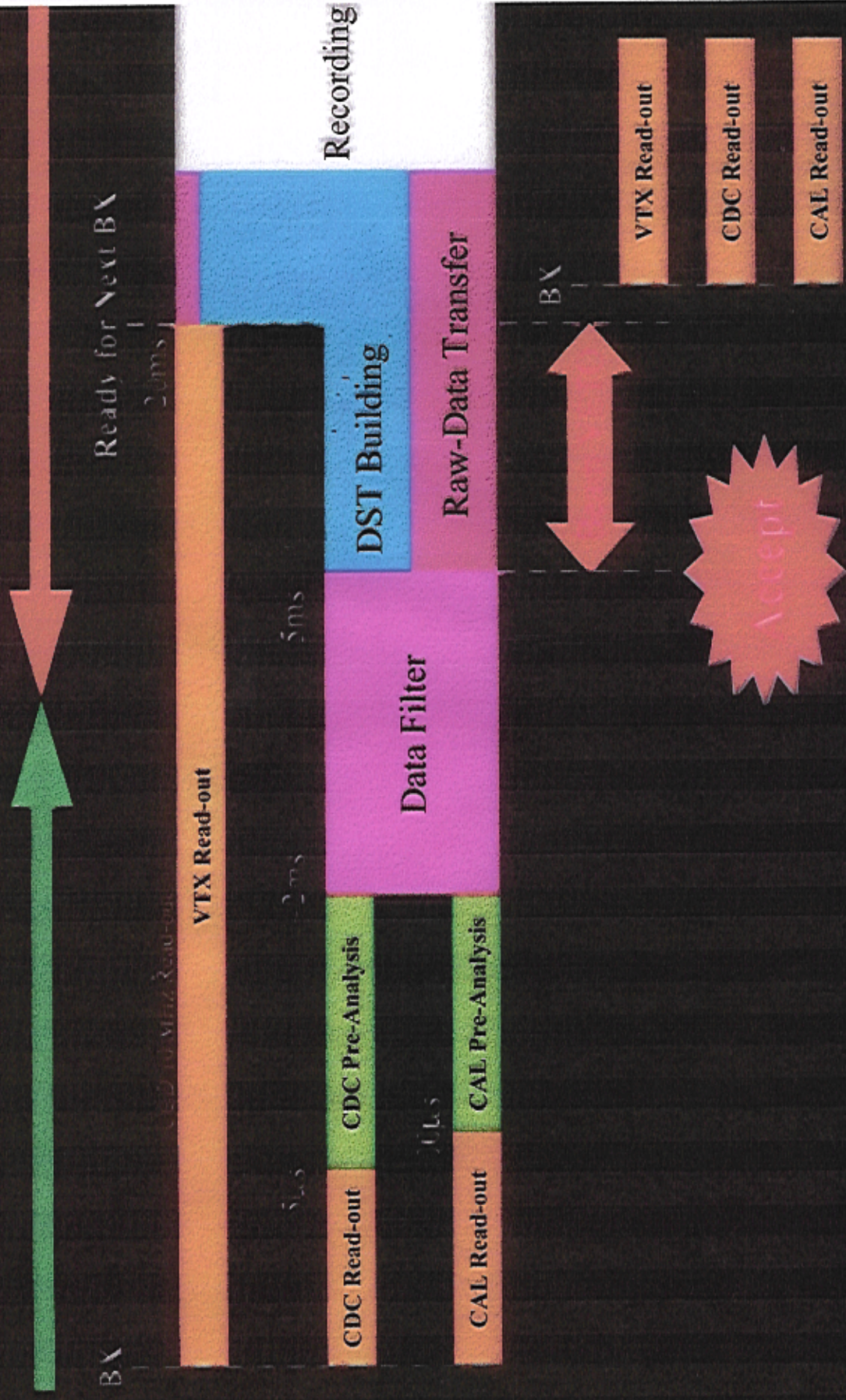
• 12 Mbytes, ~ 10 Hz $\rightarrow 120$ MB/s

– On-line DST Recording @ Z^0 Peak

• 1 Mbytes, 150 Hz $\rightarrow 150$ MB/s

$\rightarrow 10$ Tbytes / Day

\rightarrow Further Reduction may be Required for Permanent Storage



BX

Ready for Next BX

CDC to VTX Read-out

VTX Read-out

50 ns

200 ns

500 ns

CDC Read-out

CDC Pre-Analysis

Data Filter

DST Building

CAL Read-out

CAL Pre-Analysis

Raw-Data Transfer

Recording

BX

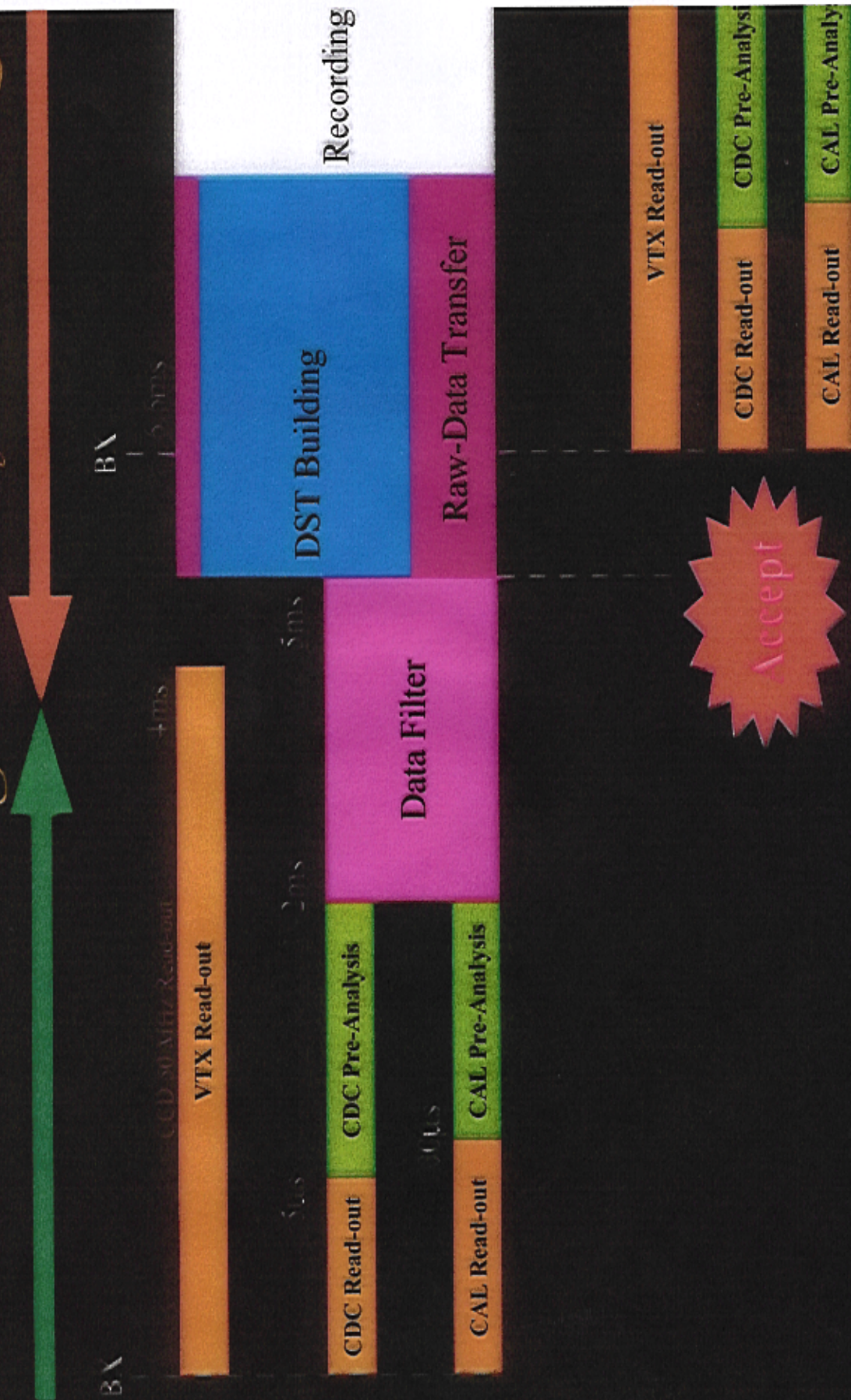
VTX Read-out

CDC Read-out

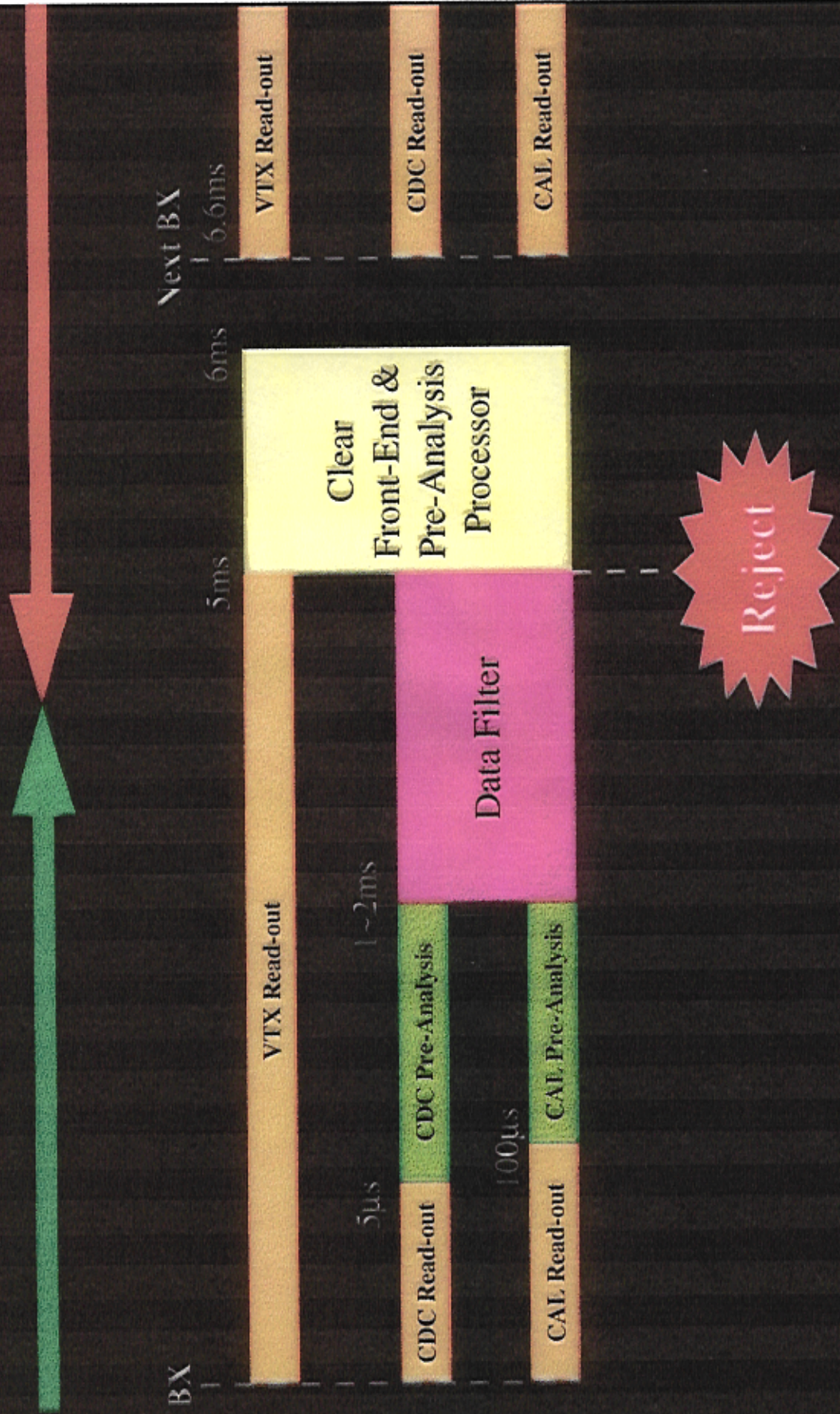
CAL Read-out

Accept

Timing Chart of JLC DAQ



4th International Workshop on Linear Colliders



Available Technologies



- Data Transfer
 - Gbps Network (ATM, FCS
 - Switches > 10 Gbps Bandwidth
- Processors
 - 10^5 MIPS, SMP Technology
- Mass Storage System
 - 100 Mbytes/s for Single HDD (FC-AL)
 - 64 Mbytes/s for Single ID-1 Tape Drive
 - TBytes Disk Array & PBytes Tape System

Milestones



- Fall 1999
 - Fix No. of Read-out Channels and Data Size
- Spring 2000
 - Complete Conceptual Design of DAQ System
- Fall 2000
 - Complete Technical Design
 - Cost Estimation based on Current Technologies